

PSMN6R4-30MLD

N-channel 30 V, 6.4 m Ω logic level MOSFET in LFPAK33 using NextPowerS3 Technology

21 January 2019

Product data sheet

1. General description

Logic level gate drive N-channel enhancement mode MOSFET in an LFPAK33 package. The NextPowerS3 portfolio, utilising Nexperia's unique "SchottkyPlus" technology, delivers high efficiency and the low spiking performance usually associated with MOSFETs with an integrated Schottky or Schottky-like body diode but without problematic high leakage current. NextPowerS3 is particularly suited to high efficiency applications at high switching frequencies.

2. Features and benefits

- Ultra low Q_G, Q_{GD} and Q_{OSS} for high system efficiency, especially at higher switching frequencies
- Superfast switching with soft-recovery; s-factor > 1
- · Low spiking and ringing for low EMI designs
- Unique "SchottkyPlus" technology; Schottky-like performance with < 1 μA leakage at 25 °C
- · Optimised for 4.5 V gate drive
- Low parasitic inductance and resistance
- High reliability clip bonded and solder die attach Mini Power SO8 package; no glue, no wire bonds, qualified to 175 °C
- Exposed leads for optimal visual solder inspection

3. Applications

- On-board DC-to-DC solutions for server and telecommunications
- Secondary-side synchronous rectification in telecommunication applications
- Voltage regulator modules (VRM)
- · Point-of-Load (POL) modules
- Power delivery for V-core, ASIC, DDR, GPU, VGA and system components
- Brushed and brushless motor control

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C	-	-	30	V
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 2</u>	-	-	66	Α
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>	-	-	51	W
Static char	acteristics					<u>'</u>
R _{DSon}	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ Fig. 10	-	6.9	8.3	mΩ
Dynamic c	haracteristics					<u>'</u>
Q_{GD}	gate-drain charge	I _D = 15 A; V _{DS} = 15 V; V _{GS} = 4.5 V; Fig. 12; Fig. 13	-	1.8	3	nC



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		D
2	S	source		
3	S	source		G—(F)
4	G	gate		mbb076 S
mb	D	mounting base; connected to drain	1 2 3 4 LFPAK33 (SOT1210)	

6. Ordering information

Table 3. Ordering information

Type number	Package					
	Name	Description	Version			
PSMN6R4-30MLD	LFPAK33	Plastic single ended surface mounted package (LFPAK33); 8 leads	SOT1210			

7. Marking

Table 4. Marking codes

Type number	Marking code
PSMN6R4-30MLD	6D430L

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{DS}	drain-source voltage	25 °C ≤ T _j ≤ 175 °C	-	30	V
V_{DGR}	drain-gate voltage	25 °C ≤ T_j ≤ 175 °C; R_{GS} = 20 kΩ	-	30	V
V _{GS}	gate-source voltage		-20	20	V
P _{tot}	total power dissipation	T _{mb} = 25 °C; <u>Fig. 1</u>	-	51	W
I _D	drain current	V _{GS} = 10 V; T _{mb} = 25 °C; <u>Fig. 2</u>	-	66	Α
		V _{GS} = 10 V; T _{mb} = 100 °C; <u>Fig. 2</u>	-	47	Α
I _{DM}	peak drain current	pulsed; $t_p \le 10 \mu s$; $T_{mb} = 25 \text{ °C}$; Fig. 3	-	264	Α
T _{stg}	storage temperature		-55	175	°C
T _j	junction temperature		-55	175	°C
$T_{sld(M)}$	peak soldering temperature		-	260	°C
Source-drai	n diode			'	
I _S	source current	T _{mb} = 25 °C	-	43	Α
I _{SM}	peak source current	pulsed; t _p ≤ 10 μs; T _{mb} = 25 °C	-	264	Α
Avalanche r	uggedness			-	

Symbol	Parameter	Conditions		Min	Max	Unit
DO(AL)O		I_D = 15 A; $V_{sup} \le 30$ V; R_{GS} = 50 Ω; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; unclamped; t_p = 159 μs	[1]	-	46.6	mJ

[1] Protected by 100% test

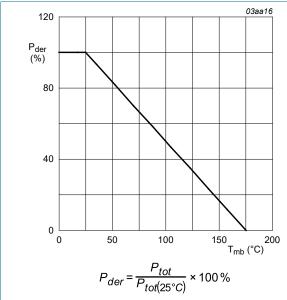


Fig. 1. Normalized total power dissipation as a function of mounting base temperature

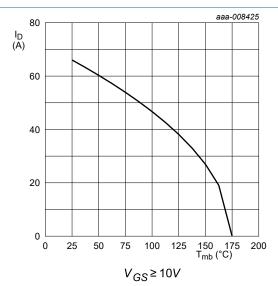


Fig. 2. Continuous drain current as a function of mounting base temperature

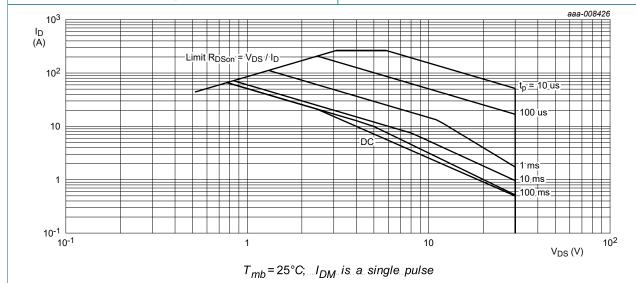


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
()/	thermal resistance from junction to mounting base	Fig. 4	-	2.72	2.94	K/W

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
	thermal resistance from junction to ambient	Fig. 5	-	57	-	K/W
		Fig. 6	-	178	-	K/W

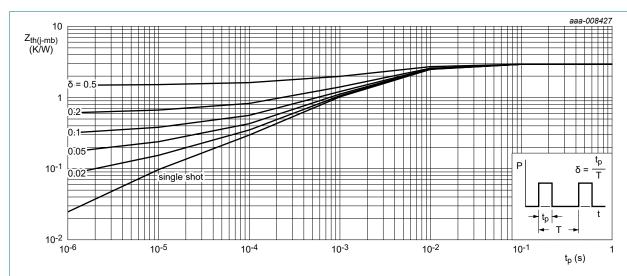


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

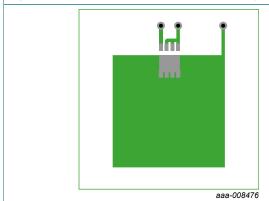


Fig. 5. PCB layout for thermal resistance junction to ambient 1" square pad; FR4 Board; 2oz copper

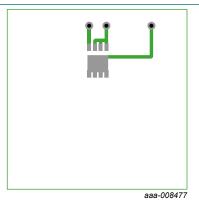


Fig. 6. PCB layout for thermal resistance junction to ambient minimum footprint; FR4 Board; 2oz copper

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit		
Static charact	Static characteristics								
V _{(BR)DSS}	drain-source	I _D = 250 μA; V _{GS} = 0 V; T _j = 25 °C		30	-	-	V		
	breakdown voltage	I _D = 250 μA; V _{GS} = 0 V; T _j = -55 °C		27	-	-	V		
V _{GS(th)}	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C}$		1.2	1.7	2.2	V		
$\Delta V_{GS(th)}/\Delta T$	gate-source threshold voltage variation with temperature	25 °C ≤ T _j ≤ 150 °C		-	-3.8	-	mV/K		
I _{DSS}	drain leakage current	$V_{DS} = 24 \text{ V}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ °C}$		-	-	1	μΑ		
		V _{DS} = 24 V; V _{GS} = 0 V; T _j = 125 °C		-	0.45	-	μΑ		
I _{GSS}	gate leakage current	V _{GS} = 16 V; V _{DS} = 0 V; T _j = 25 °C		-	-	100	nA		

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
		V _{GS} = -16 V; V _{DS} = 0 V; T _j = 25 °C	-	-	100	nA
R _{DSon}	drain-source on-state resistance	$V_{GS} = 4.5 \text{ V}; I_D = 15 \text{ A}; T_j = 25 ^{\circ}\text{C};$ Fig. 10	-	6.9	8.3	mΩ
		V_{GS} = 4.5 V; I_{D} = 15 A; T_{j} = 150 °C; Fig. 10; Fig. 11	-	-	13.7	mΩ
		V_{GS} = 10 V; I_{D} = 15 A; T_{j} = 25 °C; Fig. 10	-	5.3	6.3	mΩ
		V _{GS} = 10 V; I _D = 15 A; T _j = 150 °C; Fig. 10; Fig. 11	-	-	10.4	mΩ
R _G	gate resistance	f = 1 MHz	-	2.36	5.8	Ω
Dynamic ch	aracteristics					
Q _{G(tot)}	total gate charge	I _D = 15 A; V _{DS} = 15 V; V _{GS} = 10 V; Fig. 12; Fig. 13	-	13.7	19	nC
		I _D = 15 A; V _{DS} = 15 V; V _{GS} = 4.5 V; Fig. 12; Fig. 13	-	6.5	9	nC
		I _D = 0 A; V _{DS} = 0 V; V _{GS} = 10 V	-	12.2	-	nC
Q _{GS}	gate-source charge	I _D = 15 A; V _{DS} = 15 V; V _{GS} = 4.5 V; Fig. 12; Fig. 13	-	1.7	4	nC
Q _{GS(th)}	pre-threshold gate- source charge		-	1.2	-	nC
Q _{GS(th-pl)}	post-threshold gate- source charge		-	0.5	-	nC
Q _{GD}	gate-drain charge		-	1.8	3	nC
V _{GS(pl)}	gate-source plateau voltage	I _D = 15 A; V _{DS} = 15 V; <u>Fig. 12</u> ; <u>Fig. 13</u>	-	2.2	-	V
C _{iss}	input capacitance	V _{DS} = 15 V; V _{GS} = 0 V; f = 1 MHz;	-	832	-	pF
C _{oss}	output capacitance	T _j = 25 °C; <u>Fig. 14</u>	-	587	-	pF
C _{rss}	reverse transfer capacitance		-	64	-	pF
t _{d(on)}	turn-on delay time	$V_{DS} = 15 \text{ V}; R_L = 1 \Omega; V_{GS} = 4.5 \text{ V};$	-	9	-	ns
t _r	rise time	$R_{G(ext)} = 5 \Omega$	-	16.2	-	ns
t _{d(off)}	turn-off delay time		-	10.5	-	ns
t _f	fall time		-	10.9	-	ns
Q _{oss}	output charge	$V_{GS} = 0 \text{ V}; V_{DS} = 15 \text{ V}; f = 1 \text{ MHz};$ $T_j = 25 \text{ °C}$	-	12.6	-	nC
Source-drai	in diode					
V _{SD}	source-drain voltage	$I_S = 10 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 ^{\circ}\text{C}; Fig. 15$	-	0.8	1.2	V
t _{rr}	reverse recovery time	$I_S = 15 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$	-	23.4	-	ns
Q _r	recovered charge	\/ - 4E\/, Fig. 4C	[1] -	12.6	-	nC
t _a	reverse recovery rise time		-	10.6	-	ns
t _b	reverse recovery fall time		-	12.8	-	ns
S	softness factor		-	1.2	-	

[1] includes capacitive recovery

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N-channel 30 V, 6.4 mΩ logic level MOSFET in LFPAK33 using NextPowerS3 Technology

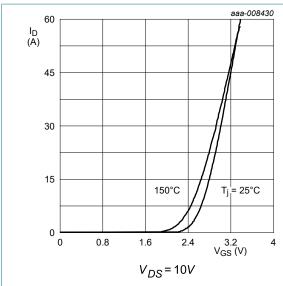


Fig. 7. Transfer characteristics; drain current as a function of gate-source voltage; typical values

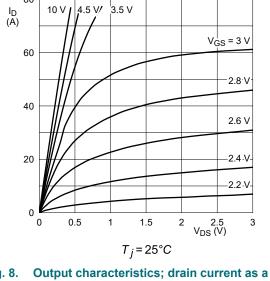


Fig. 8. Output characteristics; drain current as a function of drain-source voltage; typical values

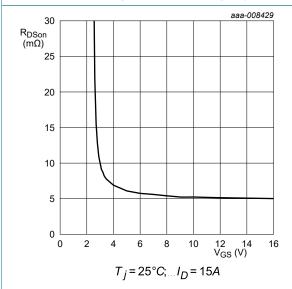


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

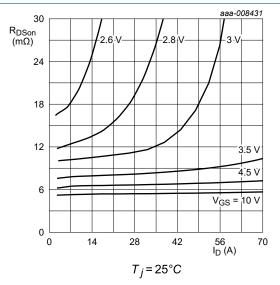


Fig. 10. Drain-source on-state resistance as a function of drain current; typical values

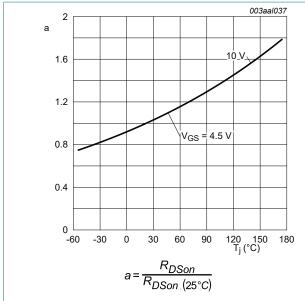


Fig. 11. Normalized drain-source on-state resistance factor as a function of junction temperature

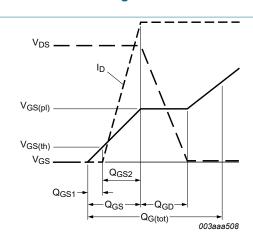


Fig. 12. Gate charge waveform definitions

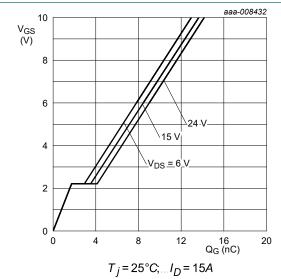


Fig. 13. Gate-source voltage as a function of gate charge; typical values

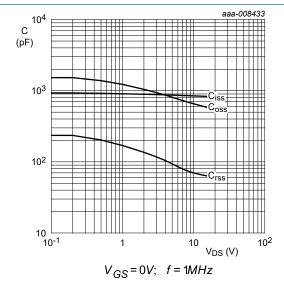


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

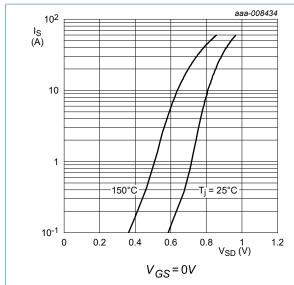


Fig. 15. Source current as a function of source-drain voltage; typical values

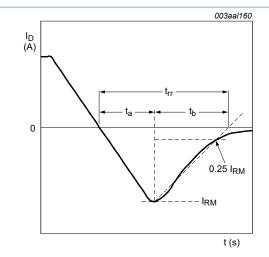


Fig. 16. Reverse recovery timing definition

11. Package outline

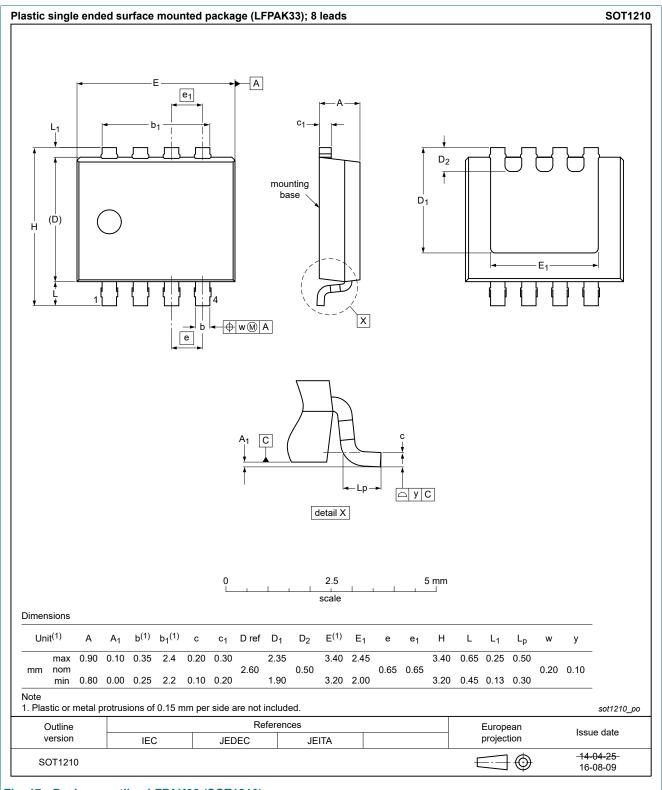
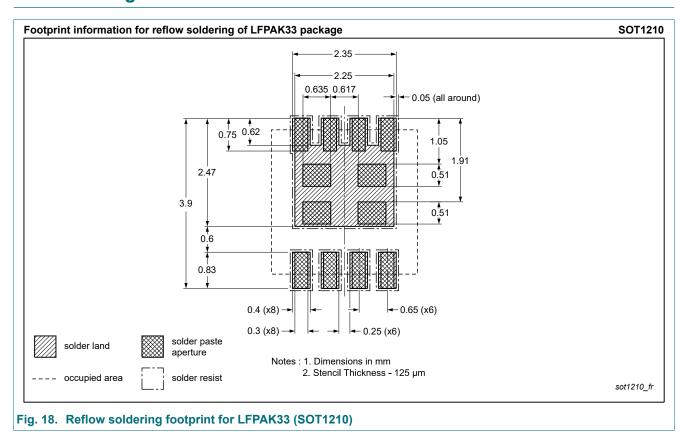


Fig. 17. Package outline LFPAK33 (SOT1210)

12. Soldering



13. Legal information

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Document status [1][2]	Product status [3]	Definition
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For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 21 January 2019

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